

**IN THE CLAIMS:**

Please cancel claims 13, 14 and 17-24 without prejudice or disclaimer.

Please amend claims 1 and 9 as shown below:

1. (Amended) A semiconductor wafer, including:

a plurality of the sections defined thereon by scribe lines, each chip section having bump electrodes formed simultaneously thereon, the scribe lines for separating the chip sections from each other without dividing bump electrodes thereon, said chip section including:

[a plurality of chip electrodes positioned on said chip section; and]

a plurality of chip electrodes positioned on said chip section; and

a plurality of interconnection layers for electrically connecting said chip electrodes and said bump electrodes,

said bump electrodes being located at positions other than over said chip electrodes,

said chip section having a center and a periphery and said interconnection layers extend from said periphery toward said center.

9. (Amended) A semiconductor wafer as in claim [1] 4, wherein each of said chip

sections has a center and a periphery and said interconnection layers extend from said periphery toward said center.